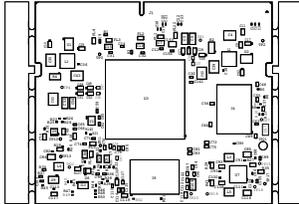


PROC131 E2 (001) ASSEMBLY TOP

ASSEMBLY NOTES:-

- 1 - All MSL components should be baked as per JEDEC standard.
- 2 - PCB should be baked at 120 degree for 8 hours.
- 3 - Board assembly must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 4 - These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5 - These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6 - Provide serial numbers to the assembled boards for identification.
- 7 - The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

AM68 PROCESSOR SK SOM TOP ASSEMBLY REV E2



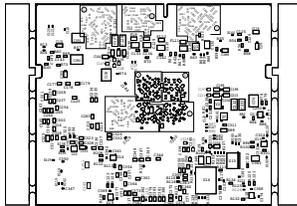
 TEXAS INSTRUMENTS		PROC131E2
BOARD NAME: AM68 PROCESSOR SK SOM BOARD	REV: E2	DESCRIPTION: TOP ASSEMBLY
SCALE: 1	DATE: 14.02.2023	SHEET 01 OF 19

PROC131 E2 (001) ASSEMBLY TOP

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AM68 PROCESSOR SK SOM BOTTOM ASSEMBLY REV E2



 TEXAS INSTRUMENTS		PROC131E2
BOARD NAME: AM68 PROCESSOR SK SOM BOARD	REV: E2	DESCRIPTION: BOTTOM ASSEMBLY
SCALE: 1	DATE: 14.02.2023	SHEET: 0F19